

Product / Package Information

Package	LFCSP - Punch
Body Size (mm)	10 X 10 X 0.85 (6.0 EP)
LeadCount	72
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.01E-01	86.91	869100	36.90	369042
Thermosets	Epoxy & Phenol Resin	Proprietary	1.48E-02	12.78	127800	5.43	54267
Other inorganic materials	Carbon black	1333-86-4	3.59E-04	0.31	3100	0.13	1316
Subtotal			1.16 E-01	100.00	1000000	42.46	424625

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.27 E-01	96.40	963989	46.68	466827
Copper & its alloys	Iron	7439-89-6	3.31 E-03	2.50	25006	1.21	12109
Copper & its alloys	Zinc	7440-66-6	7.94 E-04	0.60	6004	0.29	2907
Copper & its alloys	Phosphorus	7723-14-0	6.61 E-04	0.50	5001	0.24	2422
Subtotal			1.32 E-01	100.00	1000000	48.43	484266

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.90 E-04	100.0	1000000	0.36	3627

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.04 E-03	100.0	1000000	1.48	14800

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.24 E-03	100.0	1000000	1.55	15533

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.34 E-02	100.0	1000000	4.91	49090

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.61 E-03	73.40	734000	0.59	5916
Thermoset	Epoxy Resin	Proprietary	4.04 E-04	18.35	183500	0.15	1479
Other inorganic materials	Metal oxide	Proprietary	6.05 E-05	2.75	27500	0.02	222
Others	Curing and hardening agent	Proprietary	6.05 E-05	2.75	27500	0.02	222
Other organic materials	Gamma Butyrolactone	96-48-0	6.05 E-05	2.75	27500	0.02	222
Subtotal			2.20 E-03	100.0	1000000	0.81	8059

Package Totals			Weight (g) 2.73 E-01			Percentage (%) 100	PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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